

RD Number: RD094

RD Title: TC78S121FTG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_OSCM	1	270pF 1000V	—	—	Chip capacitor		
2	C_VCC	1	0.1μF 100V	—	—	Chip capacitor		
3	C_VDD	1	10μF 50V	—	—	Electrolytic capacitor		
4	C_VM1	1	100μF 50V	—	—	Electrolytic capacitor		
5	R_MO_AB	0	100kΩ 0.25W	—	—	Chip resistor		✓
6	R_MO_CD	0	100kΩ 0.25W	—	—	Chip resistor		✓
7	R_ALERT	1	10kΩ 0.25W	—	—	Chip resistor		
8	R_OSCM	1	120kΩ 0.25W	—	—	Chip resistor		
9	R_VRFA	0	Not mount	—	—	Variable resistor		✓
10	R_VRFB	0	Not mount	—	—	Variable resistor		✓
11	R_VRFC	0	Not mount	—	—	Variable resistor		✓
12	R_VRFD	0	Not mount	—	—	Variable resistor		✓
13	R_RSA	1	0.22Ω 0.5W	—	—	Chip resistor		
14	R_RSB	1	0.22Ω 0.5W	—	—	Chip resistor		
15	R_RSC	1	0.22Ω 0.5W	—	—	Chip resistor		
16	R_RSD	1	0.22Ω 0.5W	—	—	Chip resistor		
17	C_VM2	1	0.1μF 100V	—	—	Chip capacitor		
18	C_VRFA	1	0.1μF 100V	—	—	Chip capacitor		
19	C_VRFB	1	0.1μF 100V	—	—	Chip capacitor		
20	C_VRFC	1	0.1μF 100V	—	—	Chip capacitor		
21	C_VRFD	1	0.1μF 100V	—	—	Chip capacitor		
22	IN_C1	1	Check terminal	—	—	Check terminal		
23	IN_D2	1	Check terminal	—	—	Check terminal		
24	IN_D1	1	Check terminal	—	—	Check terminal		
25	VDD	1	Check terminal	—	—	Check terminal		
26	GND	10	Check terminal	—	—	Check terminal		

27	VREF_A	1	Check terminal	–	–	Check terminal		
28	VREF_B	1	Check terminal	–	–	Check terminal		
29	VREF_C	1	Check terminal	–	–	Check terminal		
30	VREF_D	1	Check terminal	–	–	Check terminal		
31	OSCM	1	Check terminal	–	–	Check terminal		
32	VCC	1	Check terminal	–	–	Check terminal		
33	SLEEP	1	Check terminal	–	–	Check terminal		
34	ALERT	1	Check terminal	–	–	Check terminal		
35	PHASE_A	1	Check terminal	–	–	Check terminal		
36	PHASE_B	1	Check terminal	–	–	Check terminal		
37	PHASE_C	1	Check terminal	–	–	Check terminal		
38	PHASE_D	1	Check terminal	–	–	Check terminal		
39	D_TBLANK_AB	1	Check terminal	–	–	Check terminal		
40	D_TBLANK_CD	1	Check terminal	–	–	Check terminal		
41	MODE2	1	Check terminal	–	–	Check terminal		
42	MODE1	1	Check terminal	–	–	Check terminal		
43	MODE0	1	Check terminal	–	–	Check terminal		
44	IN_A2	1	Check terminal	–	–	Check terminal		
45	IN_C2	1	Check terminal	–	–	Check terminal		
46	VM	1	Check terminal	–	–	Check terminal		
47	IN_A1	1	Check terminal	–	–	Check terminal		
48	IN_B2	1	Check terminal	–	–	Check terminal		
49	IN_B1	1	Check terminal	–	–	Check terminal		
50	SW1	1	Pin header 3P	–	–	Jumper		
51		1	Jumper socket	–	–	Jumper Short		
52	SW2	1	Pin header 3P	–	–	Jumper		
53		1	Jumper socket	–	–	Jumper Short		
54	SW3	1	Pin header 3P	–	–	Jumper		
55		1	Jumper socket	–	–	Jumper Short		
56	SW4	1	Pin header 3P	–	–	Jumper		
57		1	Jumper socket	–	–	Jumper Short		
58	SW5	0	Pin header 3P	–	–	Jumper		✓
59		0	Jumper socket	–	–	Jumper Short		✓
60	SW6	0	Pin header 3P	–	–	Jumper		✓

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